

## C1808C223J5RACTU

**Specifications** 

Insulation Resistance

Aliases (C1808C223J5RAC7800) SMD Comm X7R, Ceramic, 0.022 uF, 5%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 1808, 2.9 mm



General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	41 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	2.9mm MIN
В	0.6mm +/-0.35mm

Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

45.4545 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

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